

32ND ASEMEP TECHNICAL SYMPOSIUM (ANTS)

"Cultivating the Power of Human-Machine Collaboration: Enhancing Creativity, Inspiring Innovation, and Paving the Way for the Next Industrial Revolution through Augmented Interactions"

October 27, 2023, 8:30 AM – 10:10 AM | World Trade Center, Metro Manila, Pasay City

PSECE 2023 Convention, DAY 3 (Friday)
Morning Breakout Session (20 Presentations)

Category	Assembly Manufacturing	Quality Systems	Product & FA/REL	Test Manufacturing & Support Systems
Meeting Room	Track 1 (2F – Luna)	Track 2 (2F – Hidalgo)	Track 3 (2F – Amorsolo)	Track 4 (2F – Joya)
Moderators	Raynell Inojosa, PhD & Reggie Reyes	Ruth Jacob & Ronald Hilaria	Harold Juan & Ridor Dacasin, Ian Harvey Arellano, PhD	Edgar Santos, Chito Del Mundo & Erwin De Guzman
8:30 - 8:50 AM	[15] SURFACE IONIZATION EFFECT OF MIXED GAS Ar+H ₂ (5%) PLASMA ON ROUGHENED AND NON-ROUGHENED BARE Cu LEADFRAME	[13] DEVISING VARIATION REDUCTION TECHNIQUES FROM STATISTICAL PROCESS CONTROL SIGNALS TO ACHIEVE WIRE BOND PROCESS STABILITY	[4] INTRODUCTION OF DESCALING FOR THE IMPROVEMENT OF HALF CUT SINGULATION PROCESS OF WETTABLE QFN PACKAGES	[6] ONE-SHOT PPE DETECTION FOR BAKE OVENS USING RESNET50 CONVOLUTIONAL NEURAL NETWORK
	<i>Ampleon Philippines Inc.</i>	<i>Texas Instruments Philippines, Inc. - Clark</i>	<i>STMicroelectronics, Inc.</i>	<i>onsemi Carmona</i>
	<i>Assembly Manufacturing</i>	<i>Quality Systems</i>	<i>Product</i>	<i>Test Manufacturing</i>
	Marty Lorgino D. Pulutan	Daphne Karen P. Arenas	Rohn Kenneth L. Serapio	Michael C. Trinidad
	Matthew M. Fernandez	Mary Grace Catherine I. Valila	Alyssa Grace S. Gablan	Diego Jose L. Cabalza
	Janice M. Estolano	Ray Frederic S. De Asis	Alvin S. Soreda	Rommel M. Fajardo
8:50 - 9:10 AM	[16] FORGING THE FOUNDATION OF LIGHTS OUT STRATEGY FOR INSPECTION BY SUSTAINING PACKAGE EXCELLENCE THROUGH SMARTT SAMPLING	[14] ELIMINATION OF BROKEN WIRE AT HEEL FOR SSOP PACKAGE	[5] FLANGE-TO-RINGFRAME ADHESION ENHANCEMENT ON AIR CAVITY PACKAGE (ACP) VIA MECHANICAL SURFACE PREPARATION	[7] AN INNOVATIVE SOLUTION TO ELIMINATE MANUAL HANDLING WITH THE INTRODUCTION OF AUTO FLIPPER TECHNOLOGY FOR DEAD BUG MODULE
	<i>Texas Instruments Philippines, Inc. - Clark</i>	<i>onsemi Tarlac</i>	<i>Ampleon Philippines Inc.</i>	<i>STMicroelectronics, Inc.</i>
	<i>Assembly Manufacturing</i>	<i>Quality Systems</i>	<i>Product</i>	<i>Test Manufacturing</i>
	Mary Irene T. Reyes	Renante T. Somera	Mark Andrew T. Tabucanon	Reinadd Jan B. Abad
	Jeffrey S. Solas	-	Julius Albert C. Patalen	Judioz M. Manejero
	Mara Karissa P. Nuguid	-	Jocy P. Castillo	Carissa G. Aguila

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9:10 – 9:30 AM	[17] Pd 6NH3 2RX: NEW PALLADIUM ELECTROLYTE FORMULATION ENABLING THINNER	[15] CHALLENGING THE PROCESS AND MATERIAL CHARACTERISTIC TO ADDRESS THE HIGH EPOXY USAGE/CONSUMPTION OF VI POWER PACKAGE	[4] OUTRIGHT DETECTION OF DRIVE ROD TO DIAPHRAGM ASSEMBLY-LEVEL RELIABILITY FAILURES	[8] TEST EQUIPMENT INTELLIGENT EDGE SOLUTION FOR PACKAGE CRACK PREVENTION
	Texas Instruments Philippines, Inc. - Clark	STMicroelectronics, Inc.	Knowles Electronics (Philippines) Corporation	Analog Devices General Trias, Inc.
	Assembly Manufacturing	Quality Systems	FA/REL	Test Manufacturing
	Mharpee Gonzales	Marichu S. Amalin	Dominic John Patarata	Edson Macgregor A. Leano
	Michael Pangilinan	-	-	Ruel J. Mijares
	Jeffrey Solas	-	-	-
9:30 - 9:50 AM	[18] ELEVATING PROCESS CONTROL AND CERTIFICATION UTILIZING ALID	[16] VALUE STREAM MAPPING ON MAP AVAILABILITY AT INCOMING QC PHASE: A LEAN APPROACH TO LT REDUCTION AND MANUFACTURING EFFICIENCY IMPROVEMENT	[5] DELAMINATION ANALYSIS OF AN ALN (DIRECT BOND COPPER SUBSTRATE) USING FINITE ELEMENT ANALYSIS (FEA)	[3] REUSING OF REVERSE OSMOSIS REJECT WATER THRU CREATION OF WATER HARVESTING SYSTEM TO CONSERVE WATER & PRESERVE ENV'T...
	onsemi Tarlac	STMicroelectronics, Inc.	Integrated Micro-Electronics, Inc.	P.IMES Corporaton
	Assembly Manufacturing	Quality Systems	FA/REL	Support Systems
	Pamela Trizia S. Tarangco	Bryan M. Delos Santos	Bernard R. Abog	Van Lorenz C. Erni
	Francis S. Fernandez	Najeeb Erwin A. Lopez	Bernard Pepito D. Malolos	Jazz Dayroll A. Basubas
	Harold Carlo P. Rebuldela	Richelle D. Barcarse	Christ Vincent M. Caliwan	Rene H. Ables
9:50 -10:10 AM	[19] DEVELOPMENT AND CHALLENGES OF HIGH FEED SPEED WAFER DICING PROCESS FOR SILICON WAFERS	[17] ELIMINATION OF MIXED DEVICE ON OPERATOR-DEPENDENT PROCESSES AT FINAL TEST P1	[6] IMPACT OF DIE ATTACH FILM ELASTIC MODULUS ON ADHESION AND PACKAGE RELIABILITY	[4] DATA ANALYTICS THROUGH FAILURE CODE TRIGGER AND MULTI-LEVEL SCORECARD
	Nexperia Philippines, Inc.	onsemi Carmona	STMicroelectronics, Inc.	Knowles Electronics (Philippines) Corporation
	Assembly Manufacturing	Quality Systems	FA/REL	Support Systems
	Mark Arthur Lancion	Analiza Eugenio	Salvador Buenviaje Jr.	Raffy C. Cosep
	Kelvin Cruz	Myla Olano	Aiza Marie Agudon	Ulysis J. Sebial
	Ferdinand Callangan	Edmund Pineda	-	Neonito O. Perez Jr.

G/F Tent - 10:10 AM – 10:25 AM (MORNING BREAK & DELIBERATION OF JUDGES)

Notes: Participants are requested to go back to the G/F Tent for the Awarding Ceremony.